

EMB-Q170C

Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: There are two temperature points marginal passed but they function are normal during the thermal test.			
Test Result Summary				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	2
Defect Unsolved	0	0	0	2

Issue date	QE Manager	Test Engineer
2016 / 08 / 10	KJ Wang	Jerry Chen

Sample Configuration & Quantity Under Test

- **Model name : EMB-Q170C**
- **CPU Board : EMB-Q170C Rev. 1.00**
- **CPU : Intel Core i7-6700 3.40 GHz**
- **BIOS : R0.3 (EQH0CM03) (06/08/2016)**
- **Chipset: Intel Q170 Express Chipset**
- **Memory : innodisk / DDR4 2133 SODIMM 16GB *2 / SEC K4A8G085WB**
- **2.5" SATA HDD: WD / WD5000LPVX 500GB**
- **Test Software : Windows 8.1 / Run PassMark Burn In Test 8.1 Pro**
- **ATX Power Supply: CWT / DSA400P-C 400W**
- **CPU Cooler :**



Thermal Image Analysis

1. Test Date: 2016-07-26

2. Test Product: EMB-Q170C

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 20 Channel Thermal Recorder:

4.1.1 OMRON Inc,

4.2.2 Model: ZR-RX45

Date of Calibration: 2015/12/18

Due date of Calibration: 2016/12/17

Serial Number: H30481978

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2015/12/01

Due date of Calibration: 2016/11/30

Serial Number: 1051444

5. Test Condition:

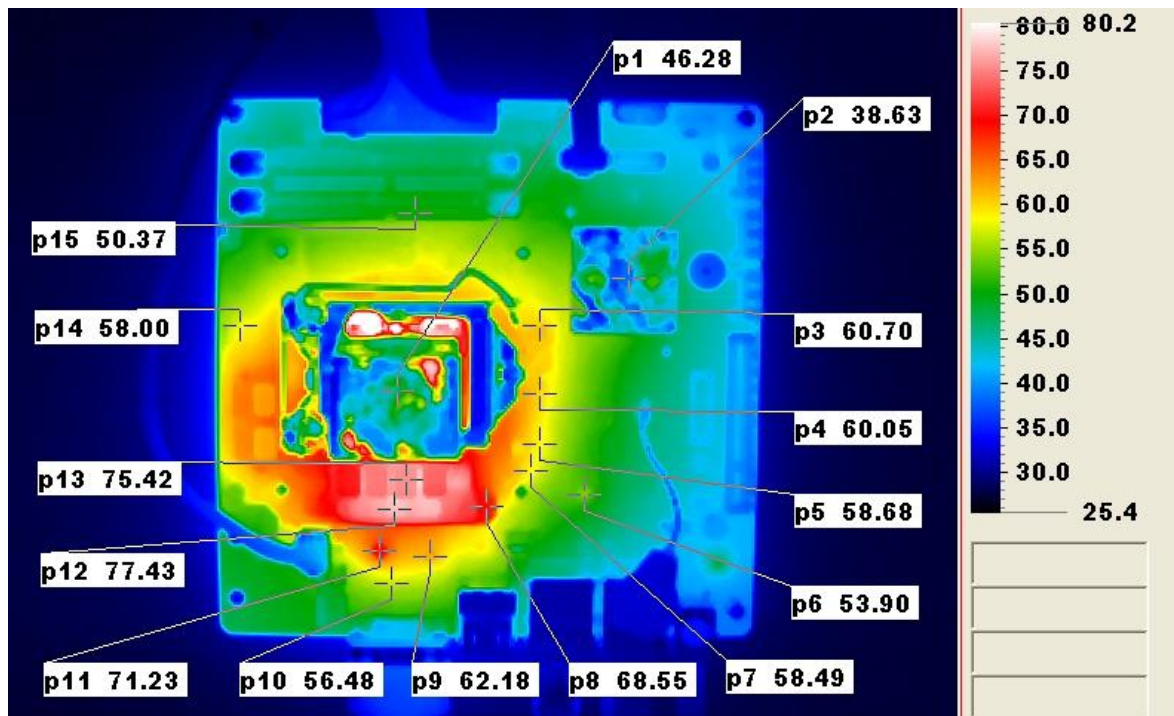
Test by DA-100: 25.0°C with Cooler (Full speed)

6. Take Picture Time:

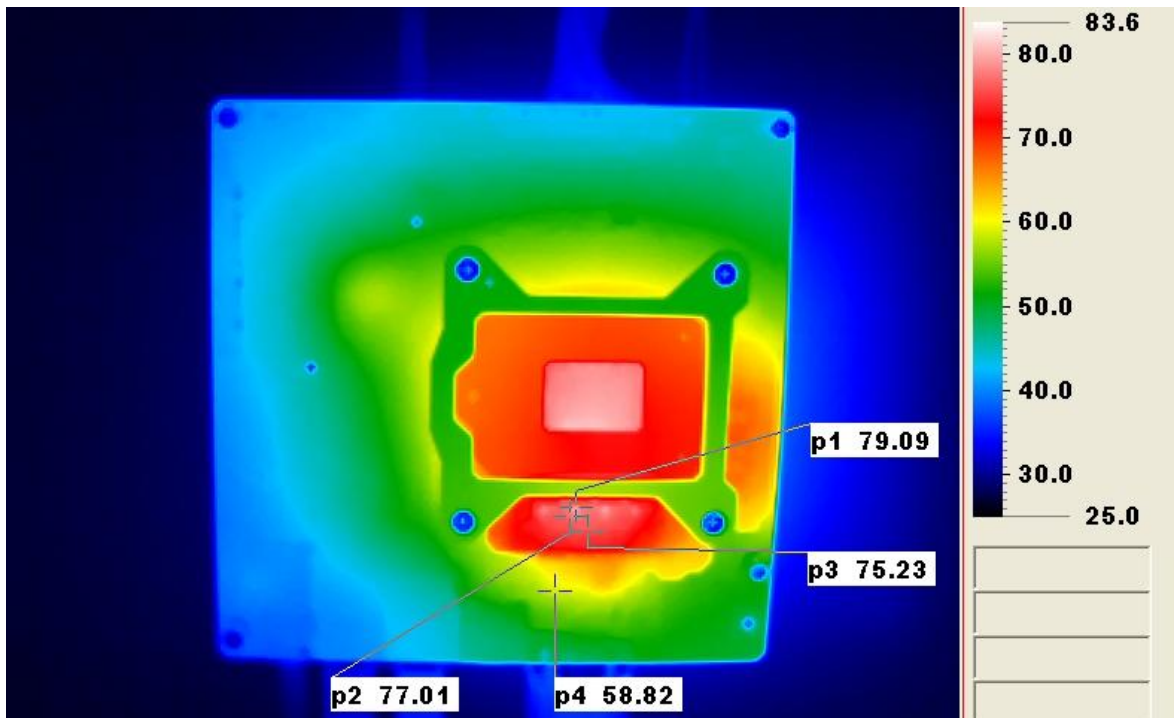
After power on 2 hours

Temperature Profile Test:

Front Side:



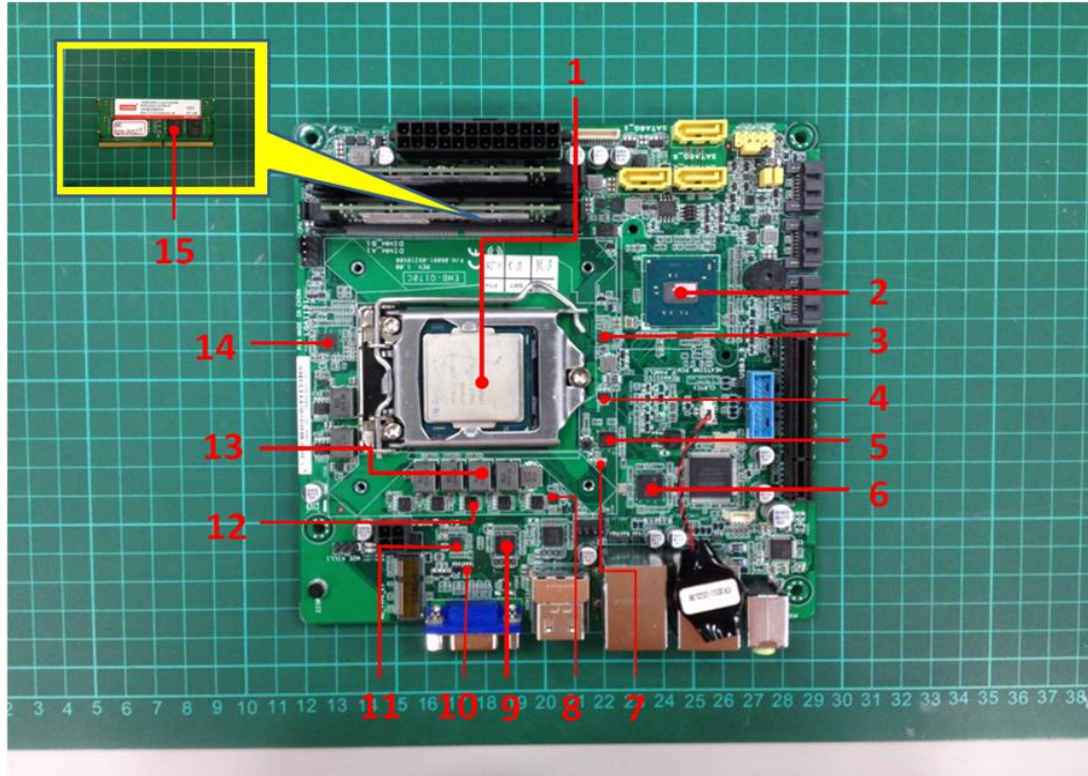
Back Side:



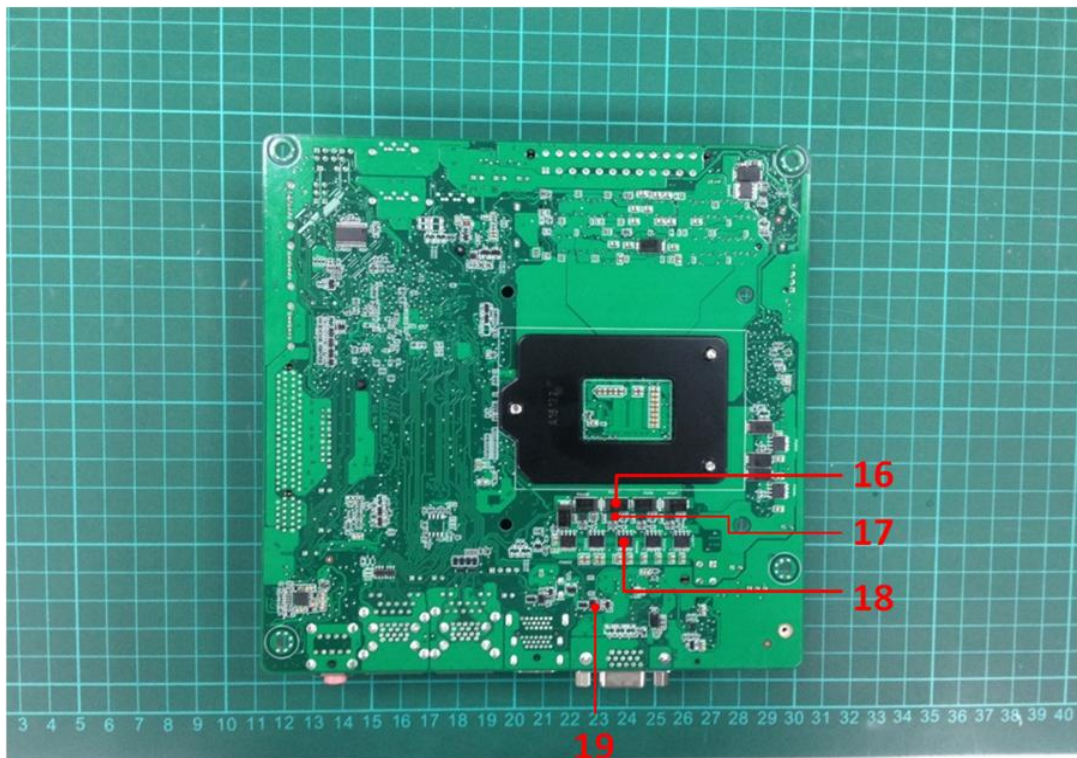
Terminal Recorder:

Measuring Thermal Couple Position :

Front Side:



Back Side:



Using OMRON Inc / ZR-RX45 test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2) TPT(*3)		Note
				25°C	60°C	
1	LGA1151	CPU Intel Core i7-6700 3.40 GHz	71	35.2	70.2	Note 6
2	SU1	PCH Q170	108	32.1	67.1	
3	PU92	PWM:HPA02240	125	32.3	67.3	
4	PQ868	NMOS:EMB45P03P	150	29.5	64.5	
5	L1U1	LAN WGI219LM	106	30.5	65.5	
6	L2U1	LAN I211AT	85	32.6	67.6	
7	L1X1	CRYSTAL 25MHZ	70	30.5	65.5	Note 6
8	PU101	PWM:RT8202M	100	35.9	70.9	
9	HU2	ASM1442K	85	37	72	
10	GU400	74LVC1G125	85	31.6	66.6	
11	GVU1	IT6516BFN	100	34.1	69.1	
12	PQ882	NMOS: PH1530CL	150	43.8	78.8	
13	PL8	POWER INDUCTOR 0.215UH/48A	125	35.6	70.6	
14	PU96	PWM: RT3607CE	100	32.2	67.2	
15	RAM	Memory chipset / SEC K4A8G085WB	95	31.9	66.9	
16	PCE3	470UF/2V (7343/D) 20%	105	40.7	75.7	
17	PU99	MOSFET DRIVER: RT9624G	100	47.3	82.3	
18	PQ880	NMOS:PH6030DLB	150	45.8	80.8	
19	U103	PCA9306DCUR	100	33.2	68.2	
20	N/A	Air Temperature	N/A	25	60	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "T_{AT}" indicates the actual measured temperature under 25°C working environmental.
3. "T_{PT}" indicates the predicted temperature under product specification.
4. **Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.
5. **RTC battery avoid to put on heat position.** Please do not exceed battery temperature specification.
6. Defect NO. : **BUL1605LABE01**